





The Delphi series Q48SQ12025, quarter brick, 36~75V input, single output, isolated DC/DC converter is the latest offering from a world leader in power system and technology and manufacturing — Delta Electronics, Inc. This product provides up to 300 watts of power in an industry standard footprint and pin out. With creative design technology and optimization of component placement, these converters possess outstanding electrical and thermal performances, as well as extremely high reliability under highly stressful operating conditions. The Q48SQ12025 offers more than 95.8% high efficiency at 25A full load. The Q48SQ12025 is fully protected from abnormal input/output voltage, current, and temperature conditions and meets all safety requirements with basic insulation.

#### **FEATURES**

- High efficiency: 95.5% @ 12V/25A
- Size:

57.9\*36.8\*11.2mm(2.28"\*1.45"\*0.44") (without heat spreader) 57.9\*36.8\*12.7mm(2.28"\*1.45"\*0.50") (with heat spreader)

- Standard footprint
- Industry standard pin out
- Fixed frequency operation
- Input UVLO, Output OCP, OVP, OTP
- Hiccup output over current protection (OCP)
- Hiccup output over voltage protection
   (OVP)
- Auto recovery OTP and input UVLO
- 1500V isolation and basic insulation
- No minimum load required
- ISO 9001, TL 9000, ISO 14001, QS9000, OHSAS18001 certified manufacturing facility
- UL/cUL 60950-1 (US & Canada)
   recognized

#### **OPTIONS**

- Latched over current protection
- Positive/Negative On/Off logic
- Latched over voltage protection
- Heat spreader optional

#### **APPLICATIONS**

- Telecom / Datacom
- Wireless Networks
- Optical Network Equipment
- Server and Data Storage
- Industrial / Testing Equipment



# **TECHNICAL SPECIFICATIONS**

(T<sub>A</sub>=25°C, airflow rate=300 LFM, V<sub>in</sub>=48Vdc, nominal Vout unless otherwise noted;

	Min.	Тур.	Max.	Units
			80	Vdc
100ms			100	Vdc
	-40		85	°C
	-55			Vdc
			1500	Vac
	36	48	75	Vdc
				Vdc Vdc
	31		33	Vdc
		_	13	A
Vin=48V, Io=0A		100		mA
Vin=48V, Io=0A		9	13	mA
D.D.H. 40 H.L. L. EH. ( COMM)		00	1	A <sup>2</sup> s
				mA dB
120112		-30		UD UD
Vin=48V, Io=0, Tc=25°C	11.88	12.00	12.12	Vdc
Vin=48V, Io=Io,min to Io,max		±10	±30	mV
			±30	mV
	11 64	±60	12 36	mV Vdc
	11.04		12.30	Vuc
Full Load, 1µF ceramic, 10µF tantalum		100	150	mV
Full Load, 1µF ceramic, 10µF tantalum		25	50	mV
0				A
Output Voltage 10% Low	30	32.5	35	Α
48V. 100uF Al Ecap.10uF Tan & 1uF Ceramic load				
cap, 0.1A/µs				
50% lo.max to 75% lo.max		250		mV
75% lo.max to 50% lo.max				mV
		300		us
		100		ms
		100		ms
Low ESR CAP (OSCON), 100% load;	0		5500	μF
				%
Vin=48V		95.4		%
			1500	Vdc
	10			MΩ
		6800		pF
		130		kHz
Van/aff at lan/aff 1 0m A	0		0.0	V
				V
VOII/OII at IOII/OII=0.0 μA			30	V
Von/off at Ion/off=1.0mA	0		0.8	V
Von/off at Ion/off=0.0 μA	2		50	V
Ion/off at Von/off=0.0V			1	mA
Logic High, Von/off=15V			50	uA
		125		%
Pout≤max rated power	-20		10	%
lo=80% of lo, max: Tc=25°C:Airflow=300LFM		2		M hou
10 30 /0 01 10; 1110A; 10-20 0; 11110W-000L1 W		50.0		grams
		65.5		gram
Refer to Figure 21 for Hot spot location (48Vin,80% lo, 200LFM,Airflow from Vin+ to Vin-)		130		°C
Refer to Figure 23 for Hot spot location		123		°C
				°C
	Vin=48V, Io=0A  P-P thru 12µH inductor, 5Hz to 20MHz 120 Hz  Vin=48V, Io=lo, Tc=25°C  Vin=48V, Io=lo,min to Io,max Vin=36V to 75V, Io=lo min Vin=48V, Tc=-40°C to 85°C over sample load, line and temperature 5Hz to 20MHz bandwidth Full Load, 1µF ceramic, 10µF tantalum Full Load, 1µF ceramic, 10µF tantalum Full Load, 1µF ceramic, 10µF tantalum  Output Voltage 10% Low  48V, 100uF AI Ecap,10µF Tan & 1µF Ceramic load cap, 0.1A/µs 50% Io.max to 75% Io.max 75% Io.max to 50% Io.max  75% Io.max to 50% Io.max  Low ESR CAP (OSCON), 100% load;  Vin=48V  Vin=48V  Vin=48V  Von/off at lon/off=1.0mA  Von/off at lon/off=0.0 µA  Ion/off at Von/off=0.0 µA  Ion/off at Von/off=15V  Over full temp range; % of nominal Vout Pout≤Max rated power  Io=80% of Io, max; Tc=25°C;Airflow=300LFM  Refer to Figure 21 for Hot spot location (48Vin,80% Io, 200LFM,Airflow from Vin+ to Vin-) Refer to Figure 21 NTC resistor location (48Vin,80% Io, 200LFM,Airflow from Vin+ to Vin-) Refer to Figure 21 NTC resistor location	36   33   31   31   31   31   31   31	36	36

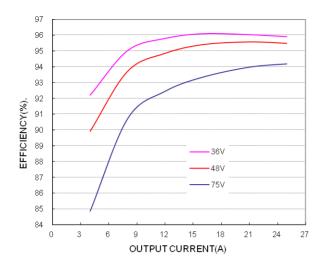


Figure 1: Efficiency vs. load current for minimum, nominal, and maximum input voltage at 25°C.

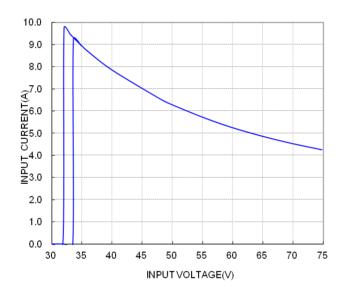


Figure 3: Typical full load input characteristics at room temperature.

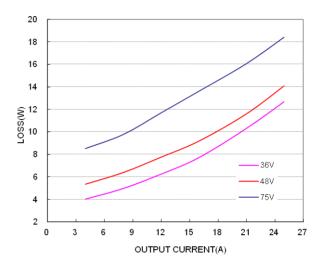
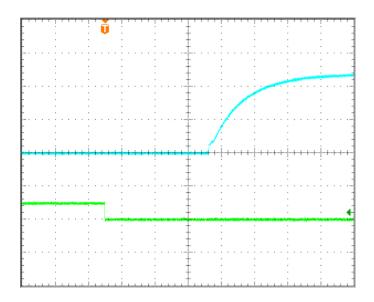
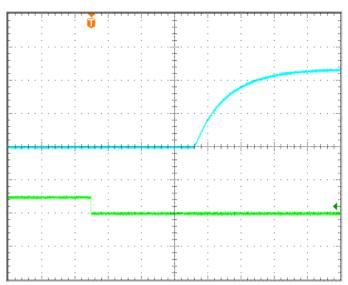


Figure 2: Power dissipation vs. load current for minimum, nominal, and maximum input voltage at 25°C.

## For Negative Remote On/Off Logic

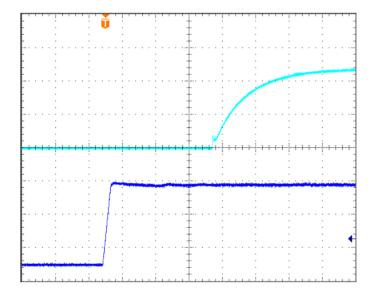


**Figure 4:** Turn-on transient at zero load current) (20ms/div). Top Trace: Vout; 5V/div; Bottom Trace: ON/OFF input: 5V/div.

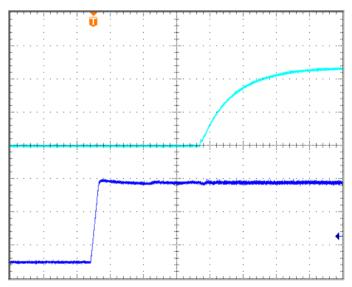


**Figure 5:** Turn-on transient at full rated load current (20 ms/div). Top Trace: Vout: 5V/div; Bottom Trace: ON/OFF input: 5V/div.

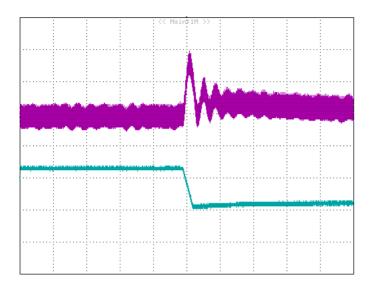
## For Input Voltage Start up



**Figure 6:** Turn-on transient at zero load current (20 ms/div). Top Trace: Vout; 5V/div; Bottom Trace: input voltage: 20V/div.



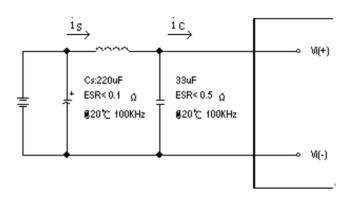
**Figure 7**: Turn-on transient at full rated load current (20 ms/div). Top Trace: Vout; 5V/div; Bottom Trace: input voltage: 20V/div.

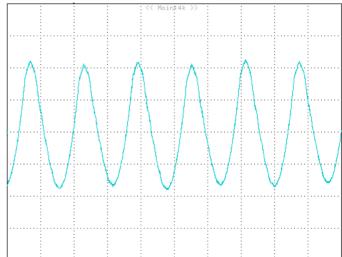


What is IM >>

**Figure 8:** Output voltage response to step-change in load current (75%-50% of Io, max; di/dt = 0.1A/µs). Load cap: 100uF Al-Electrolytic capacitor, 10µF tantalum capacitor and 1µF ceramic capacitor. Top Trace: Vout; 200mV/div; Bottom Trace: output current: 5A/div, Time: 200us/div

**Figure 9:** Output voltage response to step-change in load current (50%-75% of Io, max; di/dt = 0.1A/μs). Load cap: 100uF Al-Electrolytic capacitor, 10μF tantalum capacitor and 1μF ceramic capacitor. Top Trace: Vout; 200mV/div; Bottom Trace: output current: 10A/div, Time: 200us/div

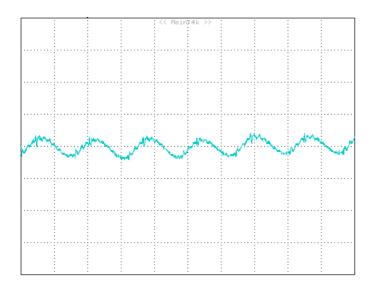




**Figure 10:** Test set-up diagram showing measurement points for Input Terminal Ripple Current and Input Reflected Ripple Current.

**Figure 11:** Input Terminal Ripple Current, i<sub>c</sub>, at full rated output current and nominal input voltage with 12μH source impedance and 33μF electrolytic capacitor (200 mA/div, 2us/div).

Note: Measured input reflected-ripple current with a simulated source Inductance ( $L_{TEST}$ ) of 12  $\mu$ H. Capacitor Cs offset possible battery impedance. Measure current as shown above.



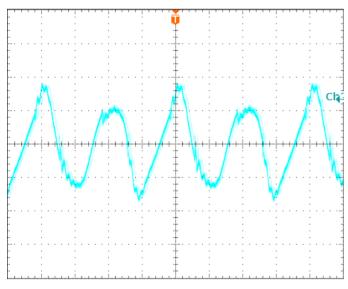
Capper Strip

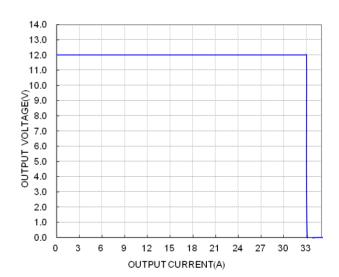
Va(+)

10u + 1u SCOPE RESISTIVE LOAD

**Figure 12:** Input reflected ripple current,  $i_s$ , through a 12 $\mu$ H source inductor at nominal input voltage and rated load current (20 mA/div, 2us/div).

Figure 13: Output voltage noise and ripple measurement test setup.





**Figure 14:** Output voltage ripple at nominal input voltage and rated load current (Io=33A)(30 mV/div, 2us/div)
Load capacitance: 1μF ceramic capacitor and 10μF tantalum capacitor. Bandwidth: 20 MHz.

Figure 15: Output voltage vs. load current at nominal input voltage showing typical current limit curves and converter shutdown points.

## **DESIGN CONSIDERATIONS**

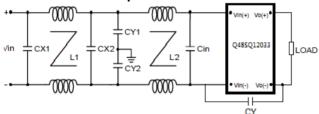
## **Input Source Impedance**

The impedance of the input source connecting to the DC/DC power modules will interact with the modules and affect the stability. A low ac-impedance input source is recommended. If the source inductance is more than a few  $\mu$ H, we advise adding a  $10\mu$ F to  $100\mu$ F electrolytic capacitor (ESR < 0.7  $\Omega$  at 100~kHz) mounted close to the input of the module to improve the stability.

## **Layout and EMC Considerations**

Delta's DC/DC power modules are designed to operate in a wide variety of systems and applications. For design assistance with EMC compliance and related PWB layout issues, please contact Delta's technical support team. An external input filter module is available for easier EMC compliance design. Below is the reference design for an input filter tested with Q48SQ12025 series to meet class B in CISSPR 22.

#### **Schematic and Components List:**



Cin is 100uF low ESR Aluminum cap:

CY is 1nF ceramic cap:

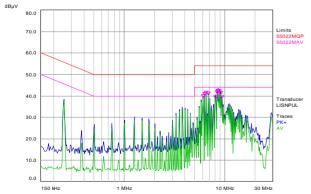
CX1 is 1uF\*3 ceramic cap;

CX2 is 1uF\*2 ceramic cap;

CY1,CY2 are 100nF\*2 ceramic cap:

L1,L2 are common-mode inductor,L1=L2=0.47mH.

Test Result:Vin=48V,lo=25A,



Blue Line is guasi peak mode; Green line is average mode.

## **Safety Considerations**

The power module must be installed in compliance with the spacing and separation requirements of the end-user's safety agency standard, i.e., UL60950-1, CAN/CSA-C22.2, No. 60950-1 and EN60950-1+A11 and IEC60950-1, if the system in which the power module is to be used must meet safety agency requirements.

Basic insulation based on 75 Vdc input is provided between the input and output of the module for the purpose of applying insulation requirements when the input to this DC-to-DC converter is identified as TNV-2 or SELV. An additional evaluation is needed if the source is other than TNV-2 or SELV.

When the input source is SELV circuit, the power module meets SELV (safety extra-low voltage) requirements. If the input source is a hazardous voltage which is greater than 60 Vdc and less than or equal to 75 Vdc, for the module's output to meet SELV requirements, all of the following must be met:

- The input source must be insulated from the ac mains by reinforced or double insulation.
- The input terminals of the module are not operator accessible.
- If the metal baseplate is grounded, the output must be also grounded.
- A SELV reliability test is conducted on the system where the module is used, in combination with the module, to ensure that under a single fault, hazardous voltage does not appear at the module's output.

When installed into a Class II equipment (without grounding), spacing consideration should be given to the end-use installation, as the spacing between the module and mounting surface have not been evaluated.

The power module has extra-low voltage (ELV) outputs when all inputs are ELV.

This power module is not internally fused. To achieve optimum safety and system protection, an input line fuse is highly recommended. The safety agencies require a normal-blow fuse with 20A maximum rating to be installed in the ungrounded lead. A lower rated fuse can be used based on the maximum inrush transient energy and maximum input current.

## **Soldering and Cleaning Considerations**

Post solder cleaning is usually the final board assembly process before the board or system undergoes electrical testing. Inadequate cleaning and drying may lower the reliability of a power module and severely affect the finished circuit board assembly test. Adequate cleaning and drying is especially important for un-encapsulated and/or open frame type power modules. For assistance on appropriate soldering and cleaning procedures, please contact Delta's technical support team.

## FEATURES DESCRIPTIONS

#### **Over-Current Protection**

The modules include an internal output over-current protection circuit, which will endure current limiting for an unlimited duration during output overload. If the output current exceeds the OCP set point, the modules will shut down (hiccup mode). The hiccup time will last 500ms.

The modules will try to restart after shutdown. If the overload condition still exists, the module will shut down again. This restart trial will continue until the overload condition is corrected.

#### **Over-Voltage Protection**

The modules include an internal output over-voltage protection circuit, which monitors the voltage on the output terminals. If this voltage exceeds the over-voltage threshold, the modules will shut down, (hiccup mode). The hiccup time will last 500ms.

The modules will try to restart after shutdown. If the overvoltage condition still exists, the module will shut down again. This restart trial will continue until the overvoltage condition is corrected.

#### **Over-Temperature Protection**

The over-temperature protection consists of circuitry that provides protection from thermal damage. If the temperature exceeds the over-temperature threshold the module will shut down. The module will restart after the temperature is within specification.

#### Remote On/Off

The remote on/off feature on the module can be either negative or positive logic. Negative logic turns the module on during a logic low and off during a logic high. Positive logic turns the modules on during a logic high and off during a logic low.

Remote on/off can be controlled by an external switch between the on/off terminal and the Vi (-) terminal. The switch can be an open collector or open drain.

For negative logic if the remote on/off feature is not used, please short the on/off pin to Vi (-). For positive logic if the remote on/off feature is not used, please leave the on/off pin to floating.

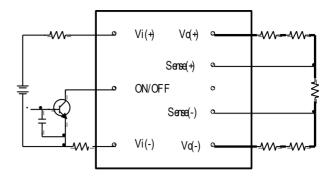


Figure 16: Remote on/off implementation

#### **Remote Sense**

Remote sense compensates for voltage drops on the output by sensing the actual output voltage at the point of load. The voltage between the remote sense pins and the output terminals must not exceed the output voltage sense range given here:

$$[Vo(+) - Vo(-)] - [SENSE(+) - SENSE(-)] \le 10\% \times Vout$$

This limit includes any increase in voltage due to remote sense compensation and output voltage set point adjustment (trim).

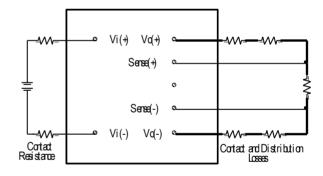


Figure 17: Effective circuit configuration for remote sense operation

If the remote sense feature is not used to regulate the output at the point of load, please connect SENSE(+) to Vo(+) and SENSE(-) to Vo(-) at the module.

The output voltage can be increased by both the remote sense and the trim; however, the maximum increase is the larger of either the remote sense or the trim, not the sum of both.

When using remote sense and trim, the output voltage of the module is usually increased. And it will increase the output power of the module with the same output current.

Care should be taken to ensure that the maximum output power does not exceed the maximum rated power.

## **Output Voltage Adjustment (TRIM)**

To increase or decrease the output voltage set point, the modules may be connected with an external resistor between the TRIM pin and either the SENSE(+) or SENSE(-). The TRIM pin should be left open if this feature is not used.

#### Trim down:

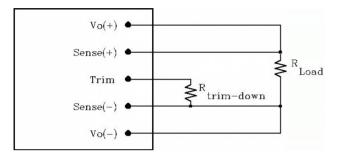


Figure 18: Circuit configuration for trim-down (decrease output voltage)

If the external resistor is connected between the TRIM and SENSE (-) pins, the output voltage set point decreases (Fig. 18). The external resistor value required to obtain a percentage of output voltage change  $\triangle$ % is defined as:

$$Rtrim - down = \frac{511}{\Lambda} - 10.2(K\Omega)$$

#### Trim up:

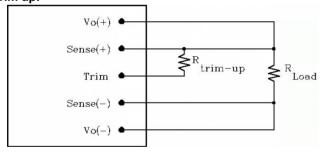


Figure 19: Circuit configuration for trim-up (increase output voltage)

If the external resistor is connected between the TRIM and SENSE (+) the output voltage set point increases (Fig. 19). The external resistor value required to obtain a percentage output voltage change  $\triangle$ % is defined as:

Rtrim - up = 
$$\frac{5.11\text{Vo} (100 + \Delta)}{1.225\Delta} - \frac{511}{\Delta} - 10.2 (K\Omega)$$

## THERMAL CONSIDERATIONS

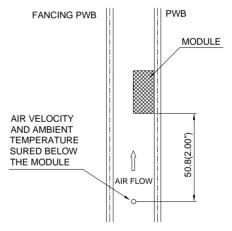
Thermal management is an important part of the system design. To ensure proper, reliable operation, sufficient cooling of the power module is needed over the entire temperature range of the module. Convection cooling is usually the dominant mode of heat transfer.

Hence, the choice of equipment to characterize the thermal performance of the power module is a wind tunnel.

#### **Thermal Testing Setup**

Delta's DC/DC power modules are characterized in heated vertical wind tunnels that simulate the thermal environments encountered in most electronics equipment. This type of equipment commonly uses vertically mounted circuit cards in cabinet racks in which the power modules are mounted.

The following figure shows the wind tunnel characterization setup. The power module is mounted on a test PWB and is vertically positioned within the wind tunnel. The space between the neighboring PWB and the top of the power module is constantly kept at 6.35mm (0.25").



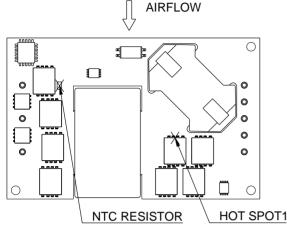
Note: Wind Tunnel Test Setup Figure Dimensions are in millimeters and (Inches)

Figure 20: Wind tunnel test setup

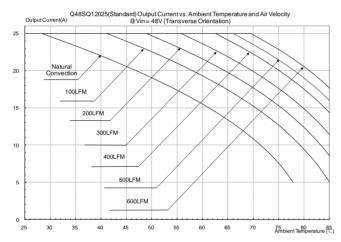
## **Thermal Derating**

Heat can be removed by increasing airflow over the module. To enhance system reliability, the power module should always be operated below the maximum operating temperature. If the temperature exceeds the maximum module temperature, reliability of the unit may be affected.

# THERMAL CURVES (WITHOUT HEAT SPREADER)

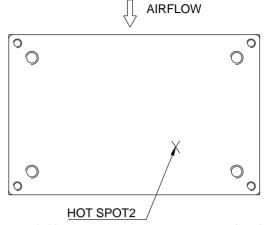


**Figure 21:** \* Hot spot1 and NTC resistor temperature measured point. The allowed maximum hot spot1 temperature is defined at 115  $^{\circ}$ C.

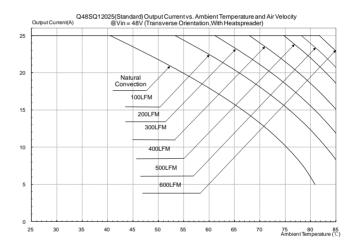


**Figure 22:** Output current vs. ambient temperature and air velocity @Vin=48V(Transverse Orientation, airflow from Vin+ to Vin-, without heat spreader)

# THERMAL CURVES (WITH HEAT SPREADER)



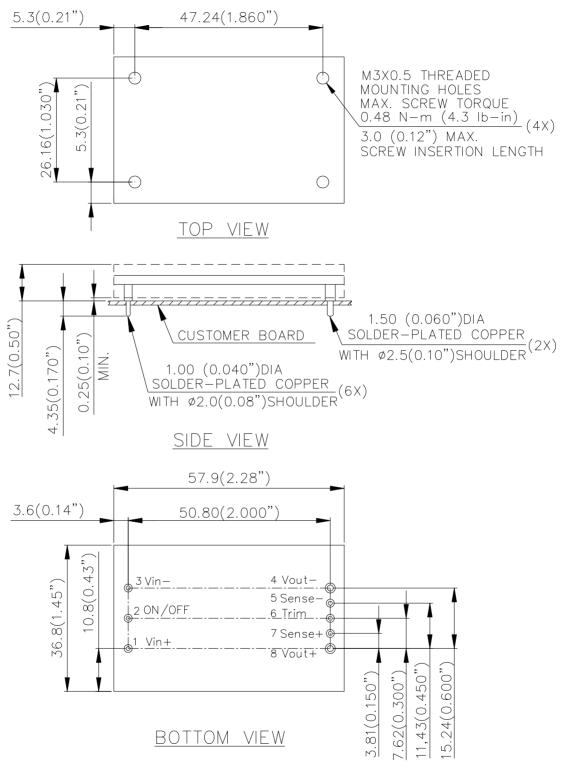
**Figure 23:** \* Hot spot2 temperature measured point. The allowed maximum hot spot2 temperature is defined at 108  $^\circ$ C.



**Figure 24:** Output current vs. ambient temperature and air velocity @Vin=48V(Transverse Orientation, airflow from Vin+ to Vin-, with heat spreader)

## **MECHANICAL DRAWING (WITH HEAT SPREADER)**

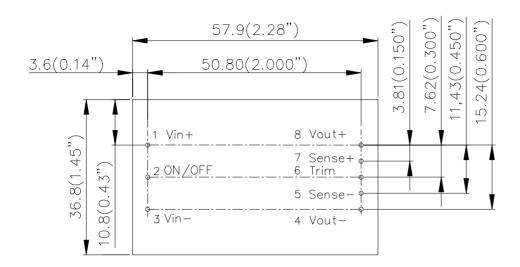
\* For modules with through-hole pins and the optional heatspreader, they are intended for wave soldering assembly onto system boards; please do not subject such modules through reflow temperature profile.



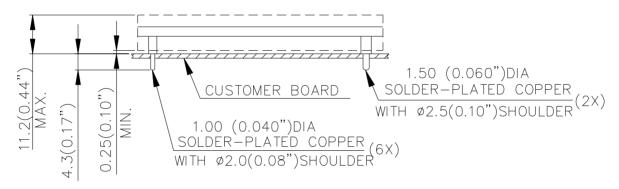
NOTES:

DIMENSIONS ARE IN MILLIMETERS AND (INCHES)
TOLERANCES: X.Xmm±0.5mm(X.XX in.±0.02 in.)
X.XXmm±0.25mm(X.XXX in.±0.010 in.)

# **MECHANICAL DRAWING (WITHOUT HEAT SPREADER)**



TOP VIEW



SIDE VIEW

NOTES:

DIMENSIONS ARE IN MILLIMETERS AND (INCHES)

TOLERANCES: X.Xmm±0.5mm(X.XX in.±0.02 in.)

X.XXmm±0.25mm(X.XXX in.±0.010 in.)

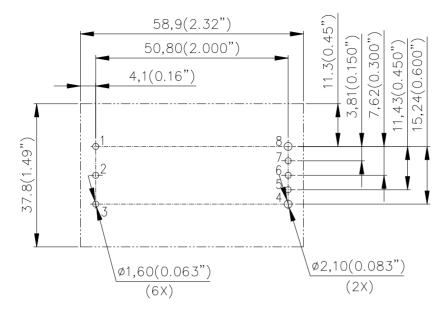
Pin No.	<u>Name</u>	<u>Function</u>
1	+Vin	Positive input voltage
2	ON/OFF	Remote ON/OFF
3	-Vin	Negative input voltage
4	-Vout	Negative output voltage
5	-Sense	Negative remote sense
6	Trim	Output voltage trim
7	+Sense	Positive remote sense
8	+Vout	Positive output voltage

### **Pin Specification:**

Pins 1-3,5~7 1.00mm (0.040") diameter Pins 4,8 1.50mm (0.060") diameter

All pins are copper alloy with matte Tin plated(Pb free) and Nickel under plating.

## RECOMMENDED LAYOUT



PIN	NAME
1	Vin(+)
2	ON/OFF
3	Vin(-)
4	Vout(-)
5	SENSE(-)
6	TRIM
7	SENSE(+)
8	Vout(+)

### PART NUMBERING SYSTEM

Q	48	S	Q	120	25	N	R	F	Н
Form	Input	Number of	Product	Output	Output	ON/OFF	Pin		
Factor	Voltage	Outputs	Series	Voltage	Current	Logic	Length		
Q - Quarter Brick	48-36V~75V	S - Single	Q- QB high power series	120 - 12V	25 - 25A	N - Negative P - Positive	N - 0.146"	(Lead Free) Space - RoHS5/6	A - with trim/ sense pin no heat spreader B - no trim/sense pin no heat spreader H - with trim/sense pin with heat spreader N - no trim/sense pin with heat spreader

<sup>\*</sup> For modules with through-hole pins and the optional heatspreader, they are intended for wave soldering assembly onto system boards; please do not subject such modules through reflow temperature profile.

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#### WARRANTY

Delta offers a two (2) year limited warranty. Complete warranty information is listed on our web site or is available upon request from Delta.

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